

# MA3X198 (MA198)

Silicon epitaxial planar type

For wave detection

### ■ Features

- Two elements contained in one package, allowing high-density mounting
- Soft recovery characteristic ( $t_{rr} = 100$  ns)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	40	V
Repetitive peak reverse voltage	$V_{RRM}$	40	V
Forward current (Average)	Single	100	mA
	Series		
Repetitive peak forward current	Single	225	mA
	Series		
Non-repetitive peak forward surge current*	Single	500	mA
	Series		
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*:  $t = 1$  s

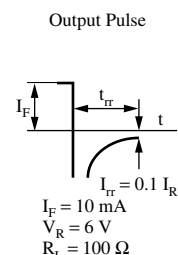
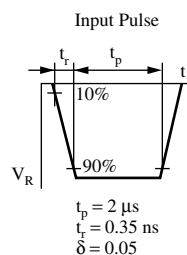
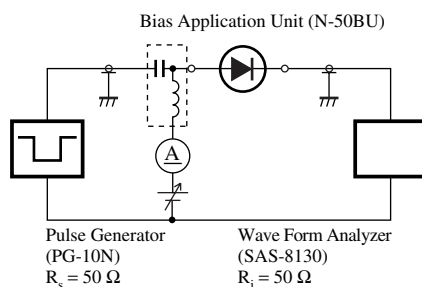
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 100 \mu\text{A}$	0.65		0.72	V
	$V_{F2}$	$I_F = 100$ mA			1.2	V
Reverse current	$I_R$	$V_R = 40$ V			10	nA
Terminal capacitance	$C_t$	$V_R = 6$ V, $f = 1$ MHz		1.0	2.0	pF
Reverse recovery time*	$t_{rr}$	$I_F = 10$ mA, $V_R = 6$ V $I_{rr} = 0.1 I_R$ , $R_L = 100 \Omega$			100	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 10 MHz.

3. \*:  $t_{rr}$  measurement circuit



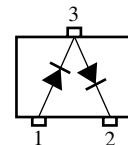
Note) The part number in the parenthesis shows conventional part number.

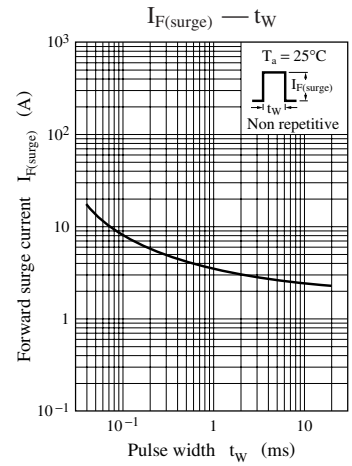
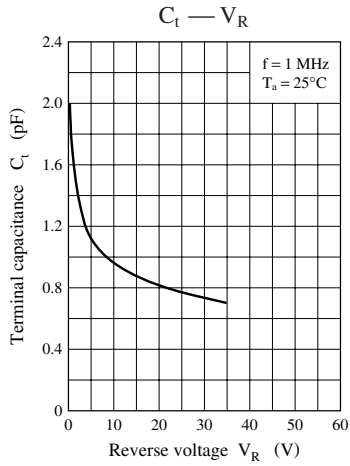
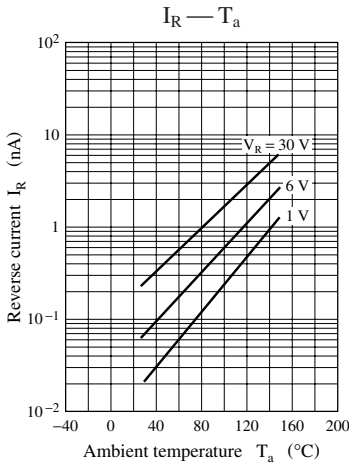
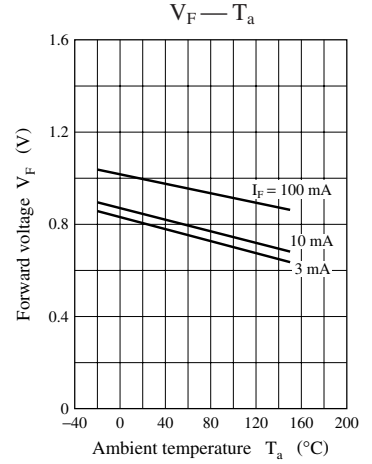
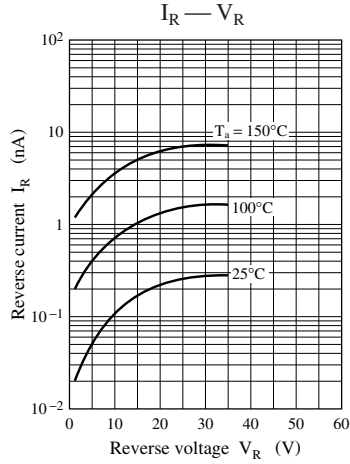
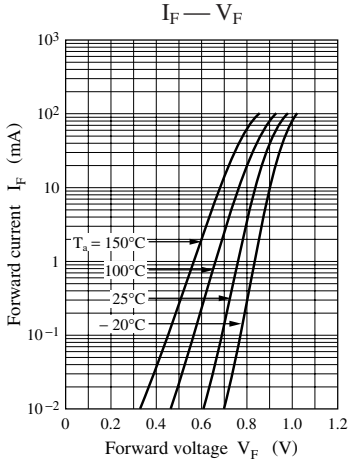
### ■ Package

- Code  
Mini3-G1
- Pin Name  
1: Anode 1  
2: Cathode 2  
3: Cathode 1, Anode 2

### ■ Marking Symbol: M2F

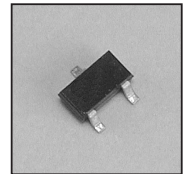
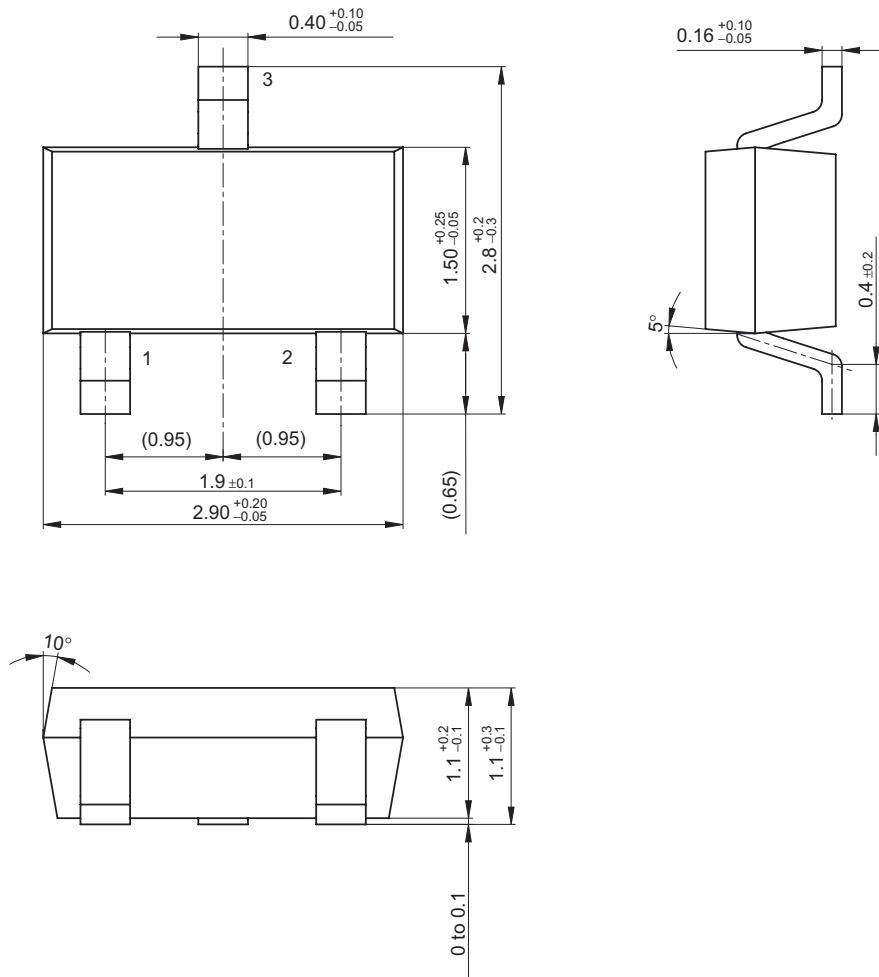
### ■ Internal Connection





Mini3-G1

Unit: mm



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